



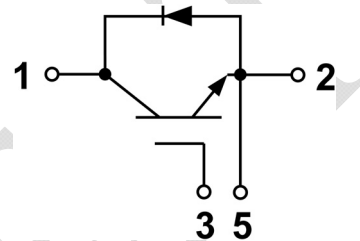
# GT600SD120T2ZH

## IGBT Module

### Features:

- Trench & Field Stop IGBT
- Short Circuit Rated > 10 $\mu$ s
- Low Switching Loss
- 100% RBSOA Tested(2 $\times$ I<sub>c</sub>)
- Low Stray Inductance
- Lead Free, Compliant with RoHS Requirement

### Circuit Diagram



### Applications:

- AC Inverter Drives
- Switched Reluctance Motor
- UPS

### IGBT, Inverter

#### Maximum Rated Values (T<sub>C</sub>=25°C unless otherwise specified)

V <sub>CES</sub>	Collector-Emitter Blocking Voltage		1200	V
V <sub>GES</sub>	Gate-Emitter Voltage		±20	V
I <sub>C</sub>	Continuous Collector Current	T <sub>C</sub> =100°C	600	A
		T <sub>C</sub> =25°C	1160	A
I <sub>CM</sub>	Peak Collector Current Repetitive	T <sub>J</sub> =175°C	1200	A
t <sub>SC</sub>	Short Circuit Withstand Time		>10	μs
P <sub>D</sub>	Maximum Power Dissipation (IGBT)	T <sub>C</sub> =25°C	3950	W
		T <sub>Jmax</sub> =175°C		



## Electrical Characteristics of IGBT ( $T_C=25^\circ\text{C}$ unless otherwise specified)

### Static Characteristics

Symbol	Description	Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=10\text{mA}$ , $V_{CE}=V_{GE}$	5.0	5.5	6.8	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$I_C=600\text{A}$ , $V_{GE}=15\text{V}$	$T_J=25^\circ\text{C}$	1.70	1.95	V
			$T_J=125^\circ\text{C}$	1.90		V
			$T_J=150^\circ\text{C}$	2.00		V
$I_{CES}$	Collector-Emitter Leakage Current	$V_{GE}=0\text{V}$ , $V_{CE}=V_{CES}$ , $T_J=25^\circ\text{C}$			1	mA
$I_{GES}$	Gate-Emitter Leakage Current	$V_{GE}=\pm 20\text{V}$ , $V_{CE}=0\text{V}$ , $T_J=25^\circ\text{C}$			800	nA
$C_{ies}$	Input Capacitance	$V_{CE}=25\text{V}$ , $V_{GE}=0\text{V}$ , $f=1\text{MHz}$		49.26		nF
$C_{oes}$	Output Capacitance			3.67		nF
$C_{res}$	Reverse Transfer Capacitance			1.85		nF

### Switching Characteristics

$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=600\text{V}$ , $I_C=600\text{A}$ , $R_{Gon}=1\Omega$ , $V_{GE}=\pm 15\text{V}$ , Inductive Load	$T_J=25^\circ\text{C}$	0.55		$\mu\text{s}$
			$T_J=125^\circ\text{C}$	0.56		
			$T_J=150^\circ\text{C}$	0.56		
$t_r$	Rise Time		$T_J=25^\circ\text{C}$	0.22		$\mu\text{s}$
			$T_J=125^\circ\text{C}$	0.22		
			$T_J=150^\circ\text{C}$	0.23		
$t_{d(off)}$	Turn-off Delay Time		$T_J=25^\circ\text{C}$	0.54		$\mu\text{s}$
			$T_J=125^\circ\text{C}$	0.57		
			$T_J=150^\circ\text{C}$	0.57		
$t_f$	Fall Time	$T_J=25^\circ\text{C}$	0.14		$\mu\text{s}$	
		$T_J=125^\circ\text{C}$	0.18			
		$T_J=150^\circ\text{C}$	0.19			
$E_{on}$	Turn-on Switching Loss	$V_{CC}=600\text{V}$ , $I_C=600\text{A}$ , $R_{Gon}=1\Omega$ , $V_{GE}=\pm 15\text{V}$ , $di/dt=2120\text{A}/\mu\text{s}$ ( $T_J=150^\circ\text{C}$ ) Inductive Load	$T_J=25^\circ\text{C}$	49.0		mJ
		$T_J=125^\circ\text{C}$	75.8			
		$T_J=150^\circ\text{C}$	81.2			



E <sub>off</sub>	Turn-off Switching Loss	V <sub>CC</sub> =600V, I <sub>C</sub> =600A, R <sub>Goff</sub> =1Ω, V <sub>GE</sub> =±15V, du/dt=2600V/μs (T <sub>J</sub> =150°C) Inductive Load	T <sub>J</sub> =25°C	81.5	mJ
			T <sub>J</sub> =125°C	96.1	
			T <sub>J</sub> =150°C	100.1	
Q <sub>g</sub>	Total Gate Charge	V <sub>GE</sub> =+15V...-15V	T <sub>J</sub> =25°C	3.36	μC
R <sub>g internal</sub>	Internal Gate Resistance		T <sub>J</sub> =25°C	1.1	Ω
RBSOA	I <sub>C</sub> =1200A, V <sub>CC</sub> =1050V, V <sub>p</sub> =1200V, R <sub>Goff</sub> = 1Ω, V <sub>GE</sub> =+15V to 0V, T <sub>J</sub> =150°C			Trapezoid	
SCSOA	V <sub>CC</sub> =600V, V <sub>GE</sub> =15V, T <sub>J</sub> =150°C			10	μs
R <sub>θJC</sub>	IGBT Thermal Resistance: Junction-to-Case			0.038	°C/W

### Diode, Inverter

#### Maximum Rated Values of Diode (T<sub>C</sub>=25°C unless otherwise specified)

V <sub>RRM</sub>	Repetitive Peak Reverse Voltage	1200	V
I <sub>F</sub>	Diode Continuous Forward Current	600	A
I <sub>FM</sub>	Diode Maximum Forward Current	1200	A

#### Electrical Characteristics of Diode (T<sub>C</sub>=25°C unless otherwise specified)

Symbol	Description	Conditions	Min.	Typ.	Max.	Units
V <sub>FM</sub>	Forward Voltage	I <sub>F</sub> =600A	T <sub>J</sub> =25°C	1.80	2.00	V
			T <sub>J</sub> =125°C	1.90		
			T <sub>J</sub> =150°C	1.90		
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =600A, -diF/dt=2270A/μs(T <sub>J</sub> =150°C), V <sub>R</sub> =600V, V <sub>GE</sub> =-15V	T <sub>J</sub> =25°C	0.37		μs
			T <sub>J</sub> =125°C	0.58		
			T <sub>J</sub> =150°C	0.65		
I <sub>rr</sub>	Peak Reverse Recovery Current	I <sub>F</sub> =600A, -diF/dt=2270A/μs(T <sub>J</sub> =150°C), V <sub>R</sub> =600V, V <sub>GE</sub> =-15V	T <sub>J</sub> =25°C	238		A
			T <sub>J</sub> =125°C	294		
			T <sub>J</sub> =150°C	306		



Q <sub>rr</sub>	Reverse Recovery Charge	I <sub>F</sub> =600A, -diF/dt=2270A/μs(T <sub>J</sub> =150°C), V <sub>R</sub> =600V, V <sub>GE</sub> =-15V	T <sub>J</sub> =25°C	52.3	μC
			T <sub>J</sub> =125°C	96.1	
			T <sub>J</sub> =150°C	110.6	
E <sub>rec</sub>	Reverse Recovery Energy		T <sub>J</sub> =25°C	22.0	mJ
			T <sub>J</sub> =125°C	38.3	
			T <sub>J</sub> =150°C	44.6	
R <sub>θJC</sub>	Diode Thermal Resistance: Junction-to-Case			0.065	°C/W

## Module

Symbol	Description	Min.	Typ.	Max.	Units
V <sub>iso</sub>	Isolation Voltage (All Terminals Shorted)	f=50Hz, 1minute	2500		V
L <sub>sCE</sub>	Stray Inductance Module			20	nH
T <sub>J</sub>	Maximum Junction Temperature			175	°C
T <sub>JOP</sub>	Maximum Operating Junction Temperature Range		-40	+150	°C
T <sub>stg</sub>	Storage Temperature		-40	+125	°C
CTI	Comparative Tracking Index		200		
R <sub>θCS</sub>	Case-to-Sink Thermally (Conductive Grease Applied)			0.03	°C/W
T	Signal Terminals Screw:M4		1.1	2.0	N·m
T	Power Terminals Screw:M6		2.5	5.0	N·m
T	Mounting Screw:M6		3.0	6.0	N·m
G	Weight			320	g



## Ordering Information Table

Device code	G	T	600	SD	120	T2Z	H
	①	②	③	④	⑤	⑥	⑦

- ① - IGBT Module
- ② - Trench, Low Switching Losses IGBT
- ③ - Rated Current (600=600A)
- ④ - Circuit Configuration (Single)
- ⑤ - Rated Voltage (120=1200V)
- ⑥ - Package Type
- ⑦ - Test Level (Pass the Important Reliability Test-Industrial Grade)

DATA SHEET

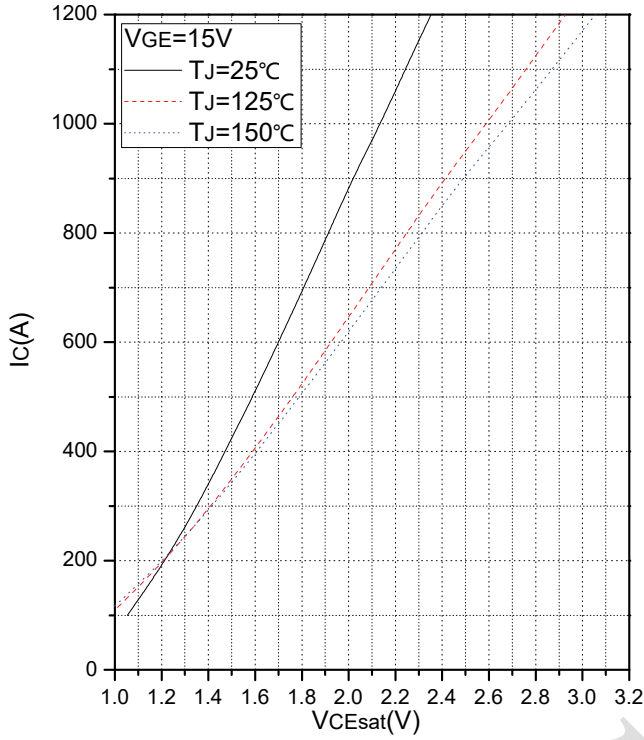


Fig.1 Typical Saturation Voltage Characteristics

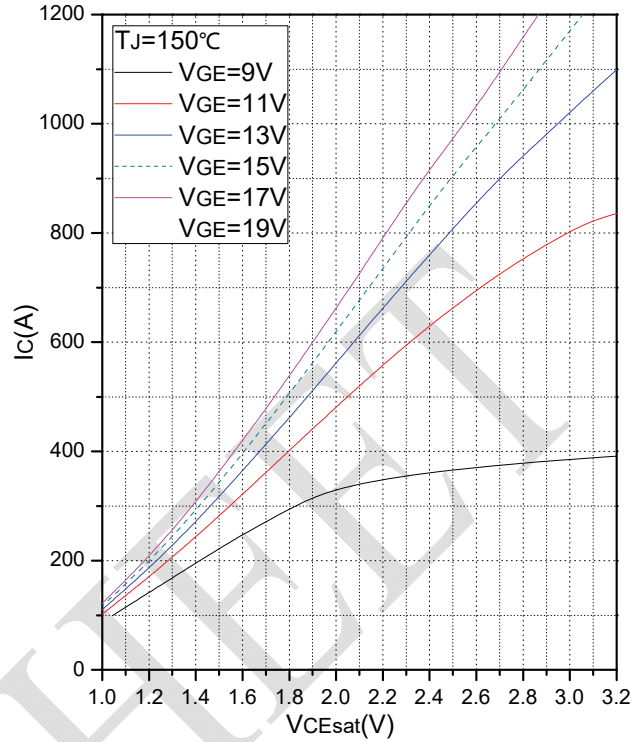


Fig.2 Typical Output Characteristics

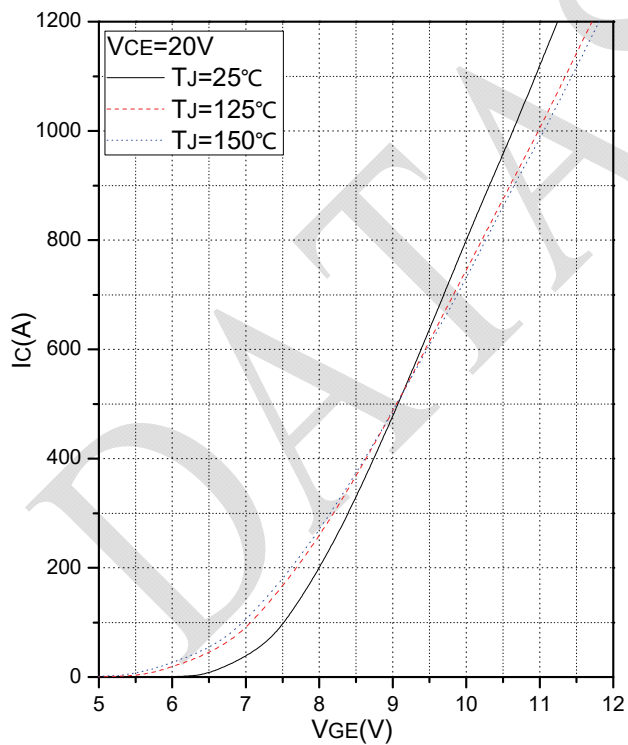


Fig.3 Transfer Characteristic

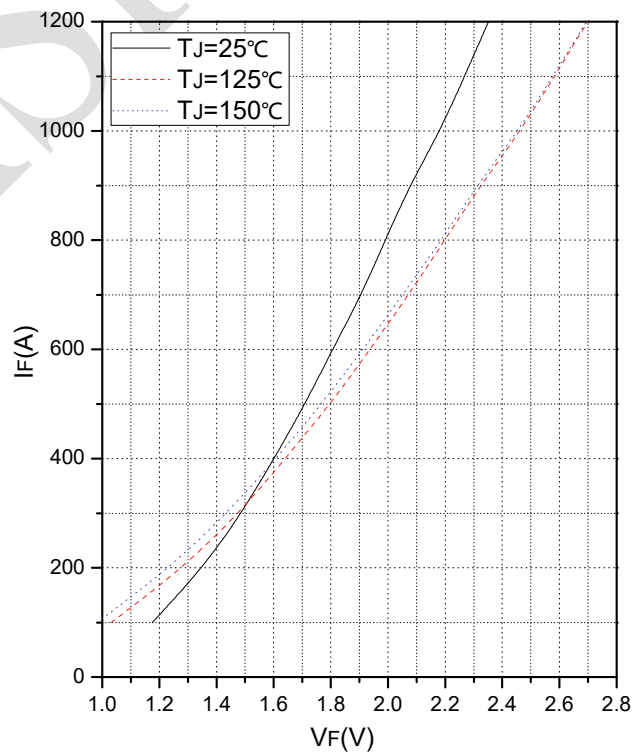


Fig.4 Forward Characteristics of Diode

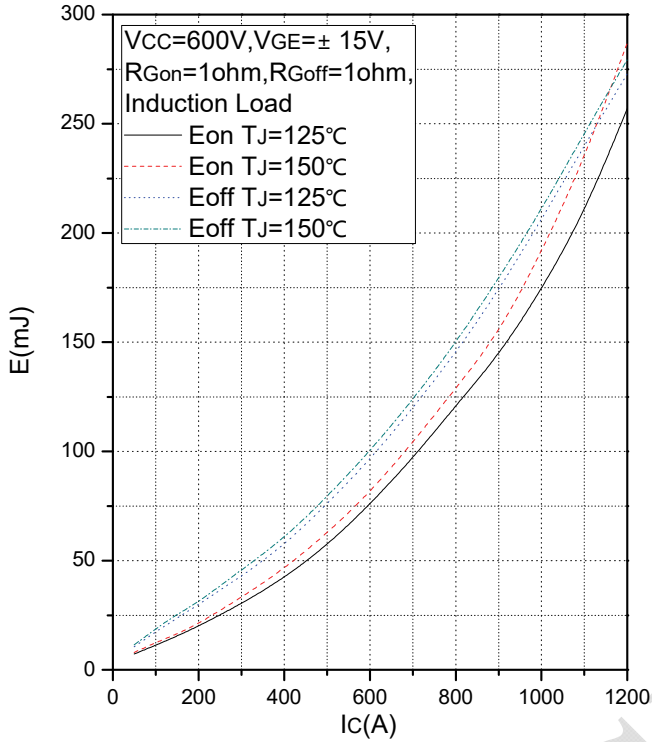


Fig.5 Typical Switching Loss vs. Collector Current

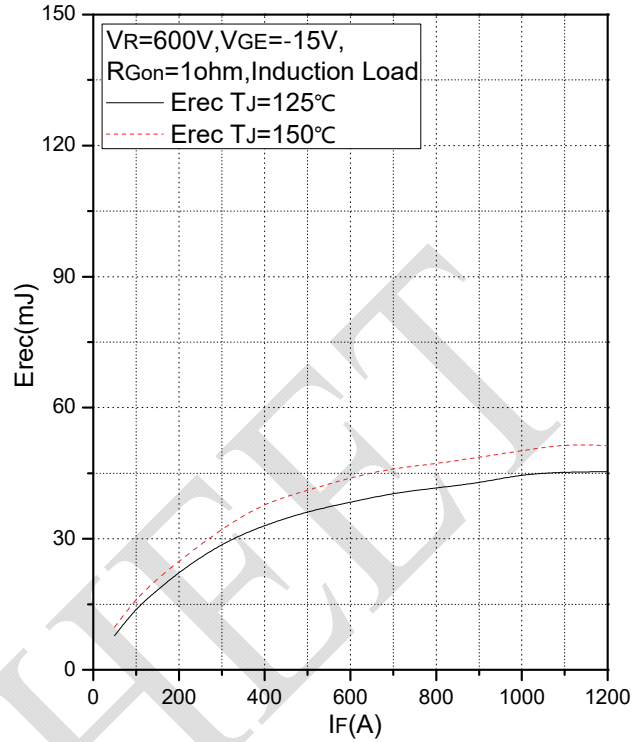


Fig.6 Typical Switching Loss vs. Forward Current

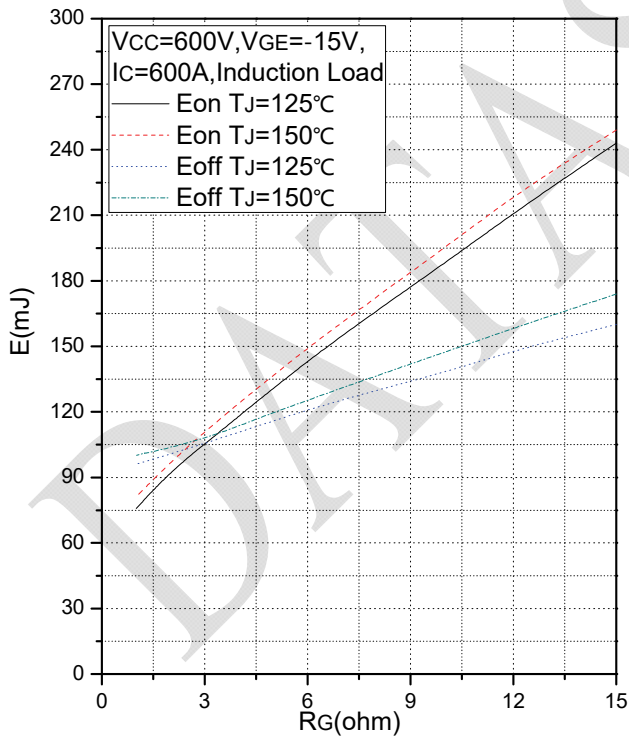


Fig.7 Typical Switching Loss vs. Gate Resistance

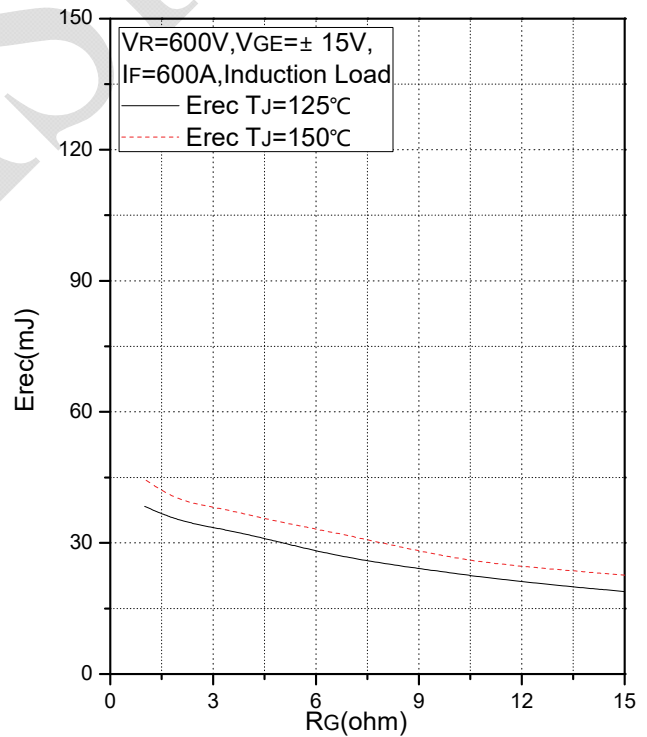


Fig.8 Typical Switching Loss vs. Gate Resistance

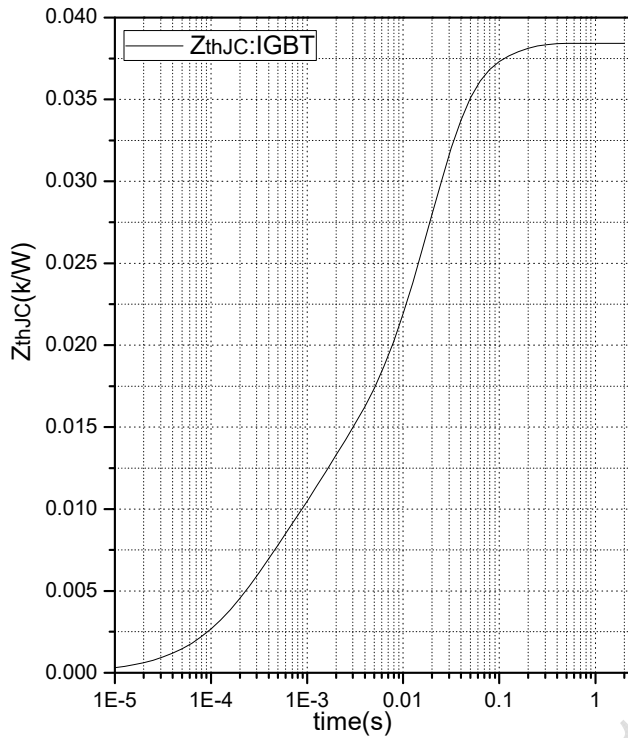


Fig.9 Transient Thermal Impedance (IGBT)

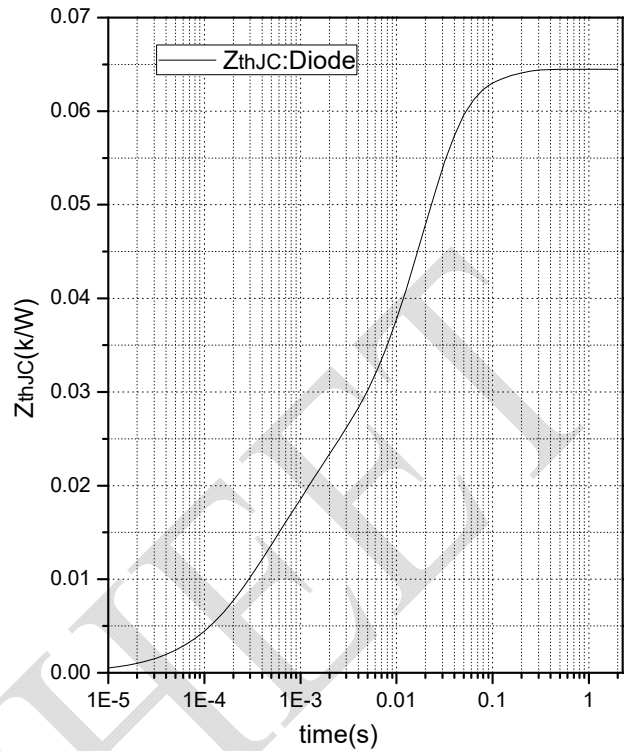


Fig.10 Transient Thermal Impedance (Diode)

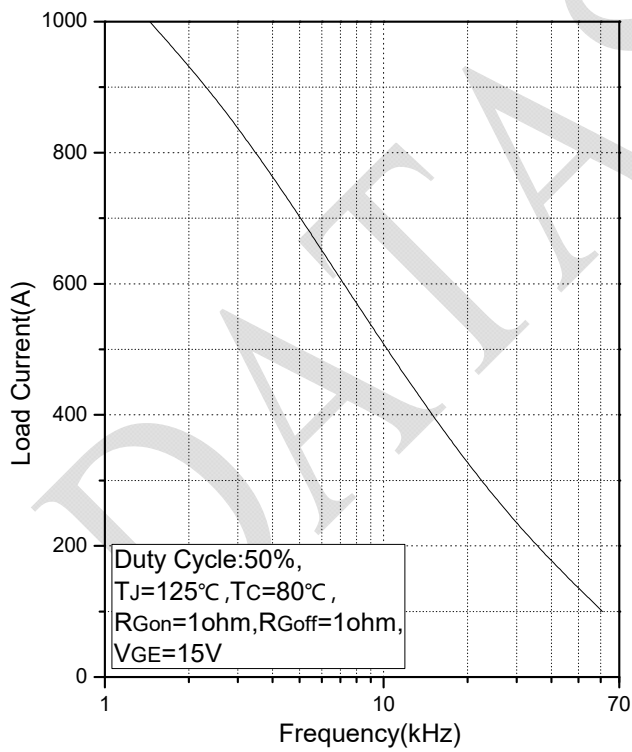


Fig.11 Typical Load Current vs. Frequency

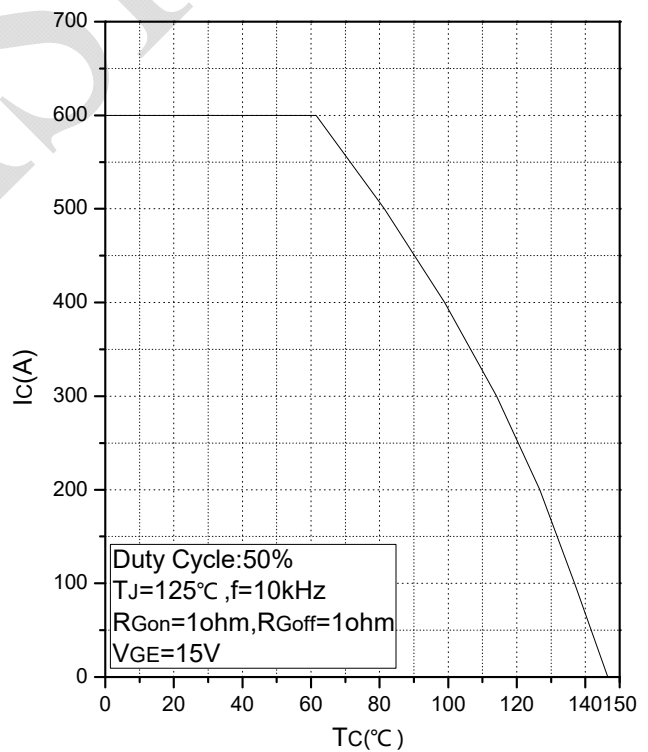


Fig.12 Rated Current vs. Temperature



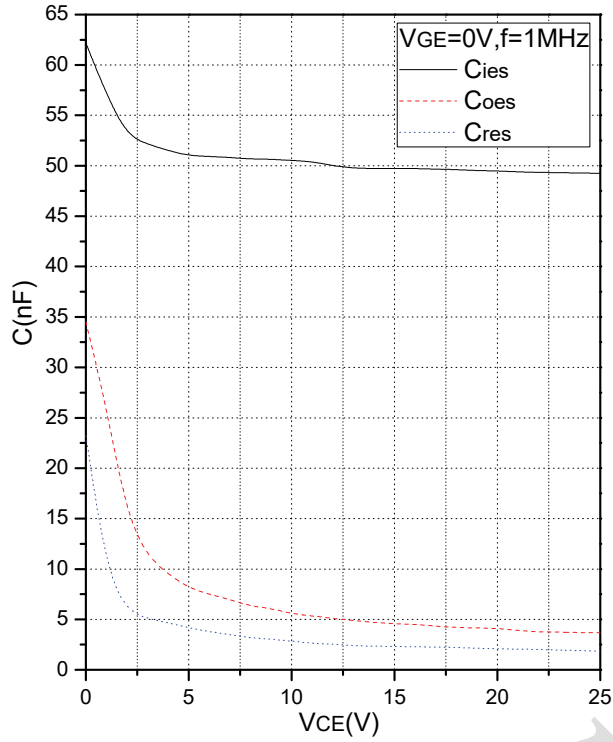


Fig.13 Capacitance Characteristics

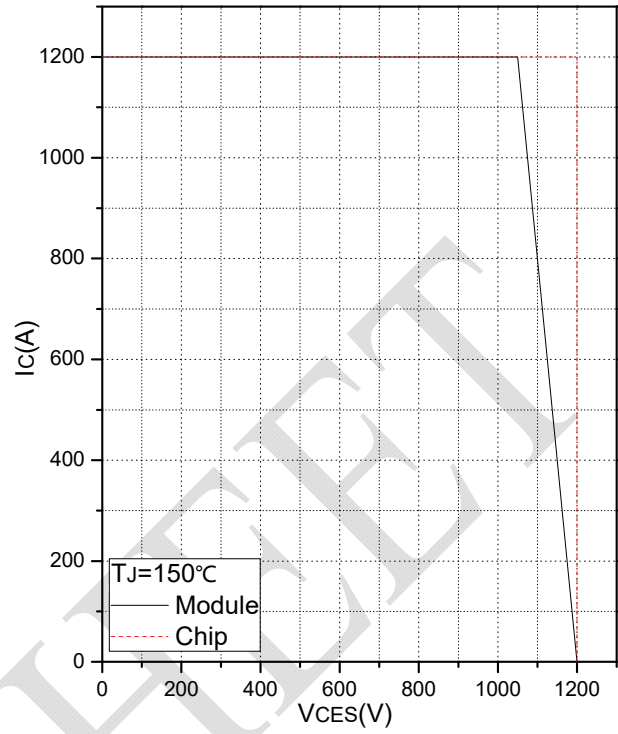
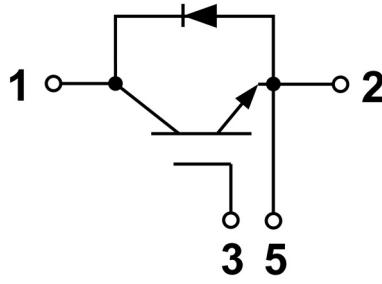


Fig.14 Reverse Bias Safe Operation Area (RBSOA)

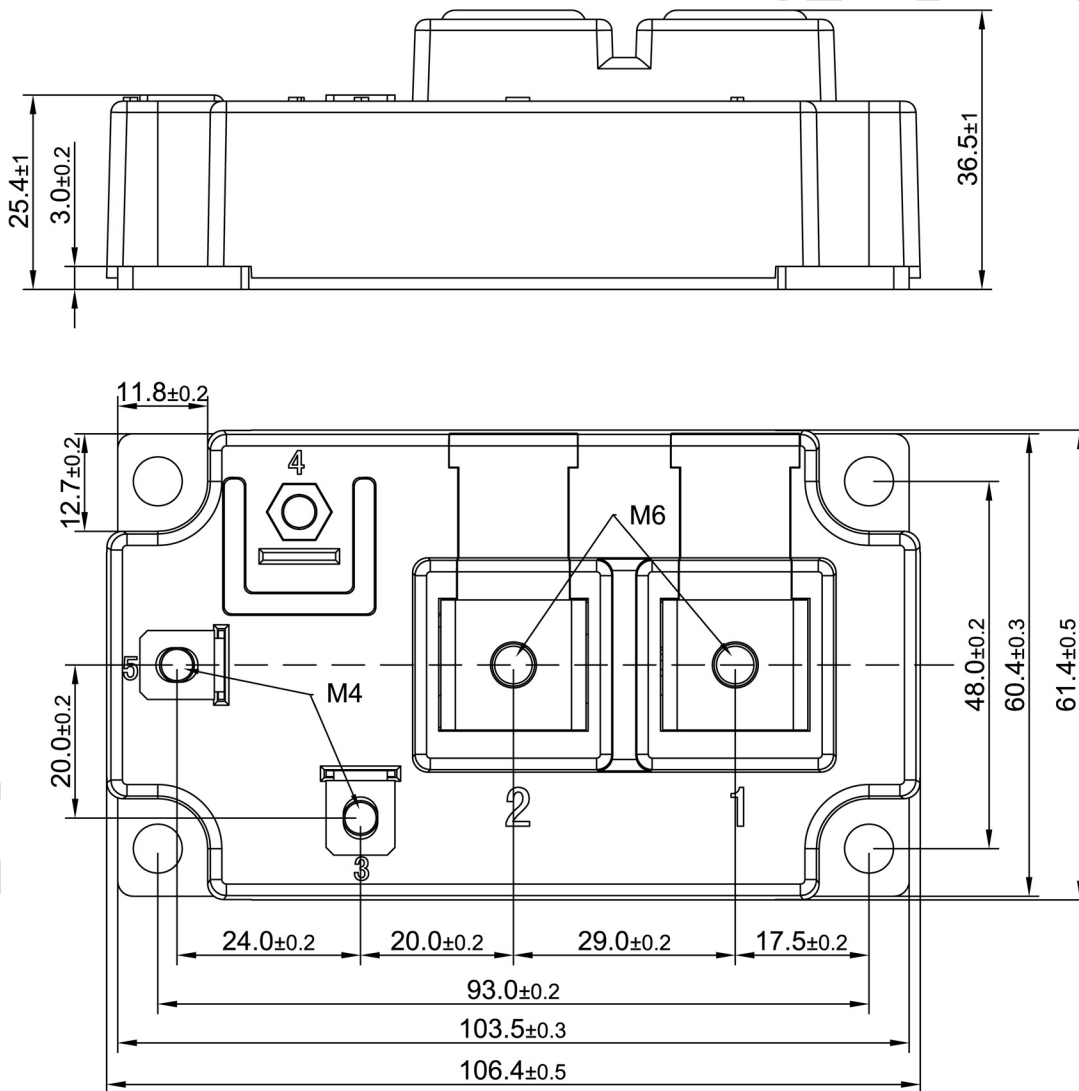
DATA SHEET



**Internal Circuit:**



**Package Outline (Unit: mm):**





Date	Revision	Notes
01/26/2022	A	Final Version

## Announcement

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